



# SOT1304-1

plastic thermal enhanced low profile quad flat package

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HLQFP176
<b>Package type industry code</b>	HLQFP176
<b>Package style descriptive code</b>	HLQFP (thermal enhanced low profile quad flat package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MS-026
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	20-4-2011

Table 1. Package summary

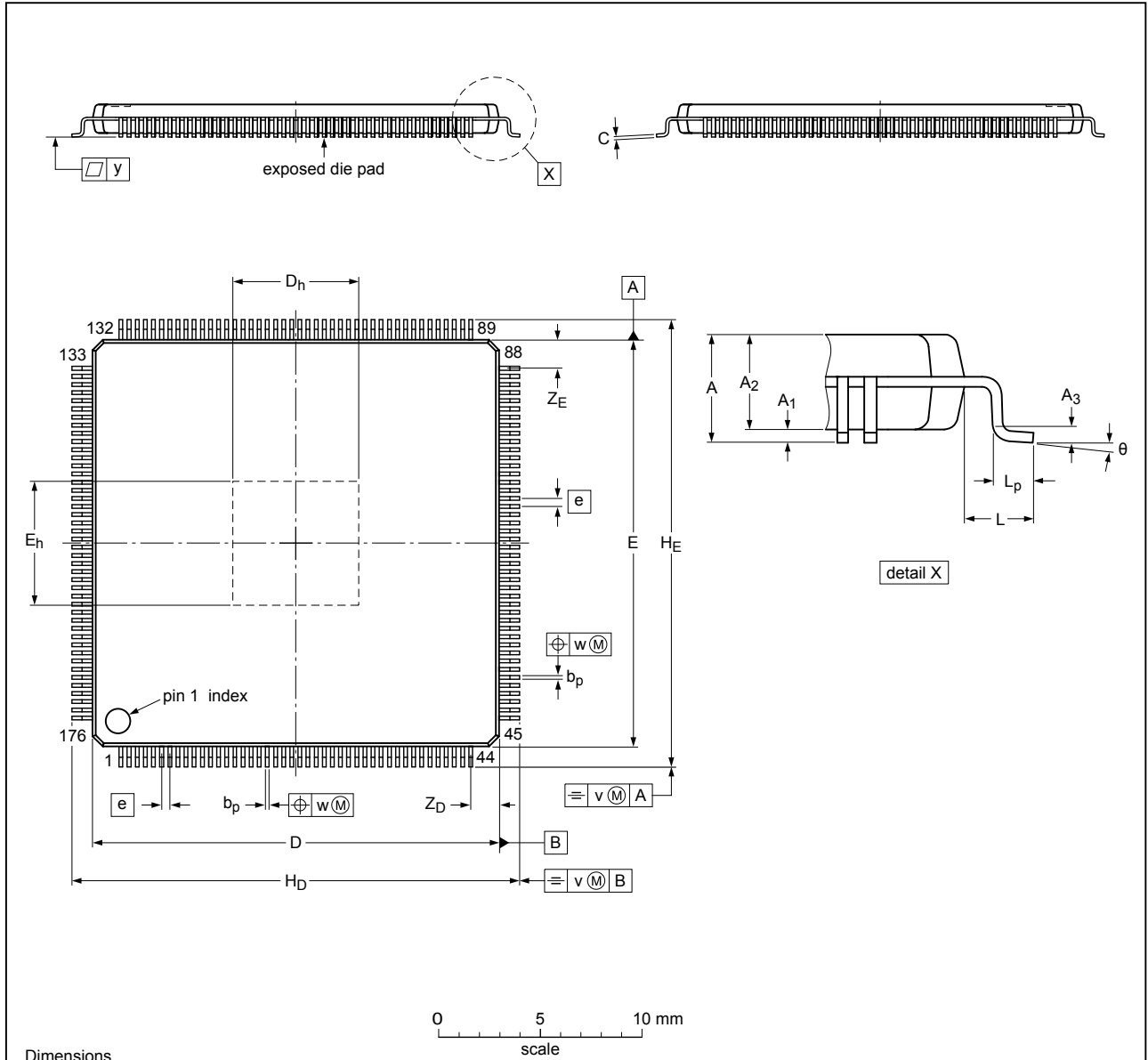
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	19.9	-	20	20.1	mm
E	package width	19.9	-	20	20.1	mm
A	seated height	1.4	-	1.5	1.6	mm
A <sub>2</sub>	package height	1.35	-	1.4	1.45	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	176	-	



## 2. Package outline

HLQFP176: plastic thermal enhanced low profile quad flat package:  
176 leads; body 20 x 20 x 1.4 mm; exposed die pad

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Dimensions

Unit <sup>(1)</sup>	A	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D	D <sub>h</sub>	E	E <sub>h</sub>	e	H <sub>D</sub>	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sub>D</sub>	Z <sub>E</sub>	θ
max	1.6	0.15	1.45		0.23	0.20	20.1	6.3	20.1	6.2		22.15	22.15		0.75		0.08	0.08	1.40	1.40	7°
nom	1.5	0.10	1.40	0.25	0.18	0.15	20.0	6.2	20.0	6.1	0.4	22.00	22.00	1	0.60	0.2	0.08	0.08	1.40	1.40	
min	1.4	0.05	1.35		0.13	0.09	19.9	6.1	19.9	5.9		21.85	21.85		0.45				1.25	1.25	0°

Note

1. plastic or metal protrusions of 0.25 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1304-1		MS-026			11-04-18 11-04-20

Fig. 1. Package outline HLQFP176 (SOT1304-1)

### 3. Legal information

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